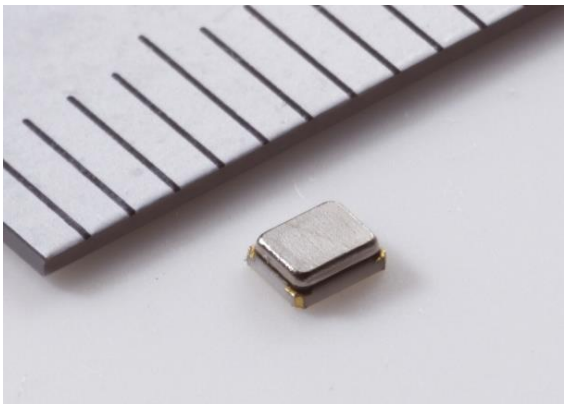
晶体谐振器 -消费用-

RoHS Lead free

muRata INNOVATOR IN ELECTRONICS



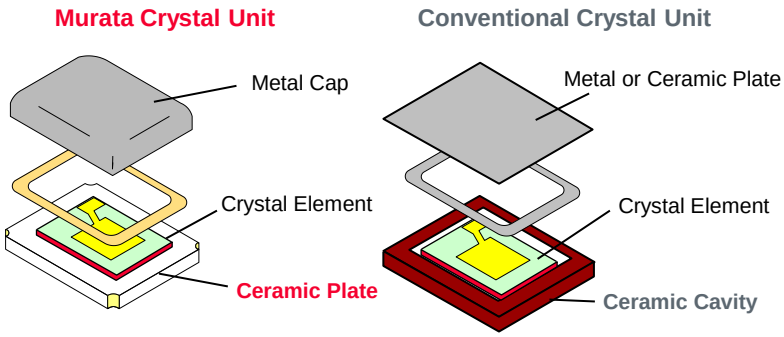
产品应用

- **无线通信**(Wi-Fi, BT, BLE, UWB,NFC, Zigbee)
- **有线通信**(Ethernet, USB2.0/3.0)
- **微机**(CPU, MPU, DSP)

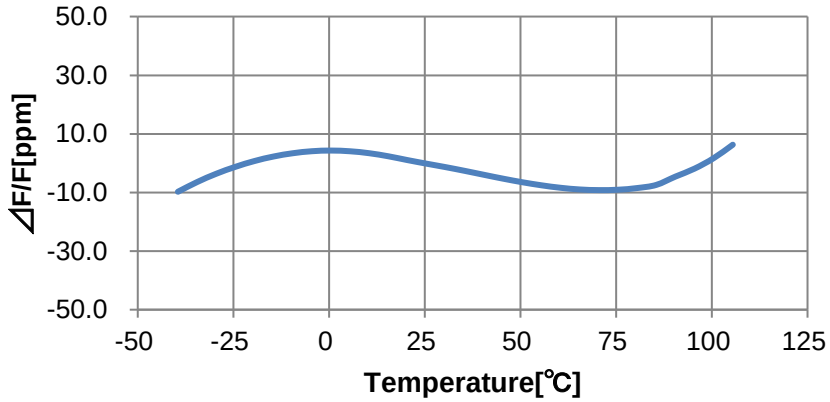
HDD, SSD, 电脑, 医疗保健, 无线模块,头戴式耳机, OTT(Over The Top), 游戏设备, 照明设备, HEMS/BEMS等

产品特性

- **小尺寸**
  16 to 50MHz: 2.0mm x 1.6mm
- **经济性与独特设计**
  使用村田独特的封装技术，结构简单
  独创的不良产品检测技术，可靠性强



温度特性

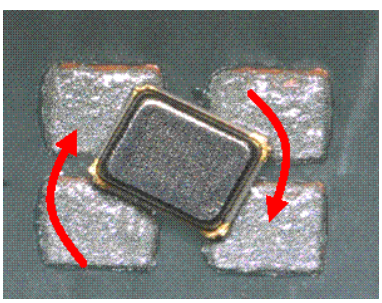


※此温度特性曲线所代表的产品为:
XRCGB25M000F3M00R0。

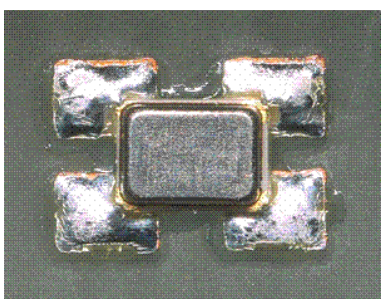
兼容性

XRCGB系列在贴装到3225晶振焊盘上后可保持正确的焊接位置

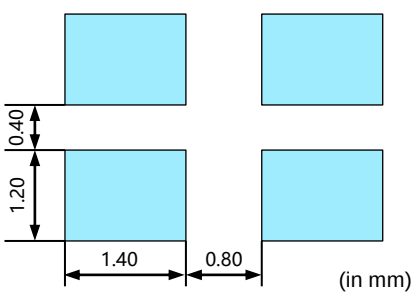
Before reflow



After reflow



实验用3225焊盘图
(Land pattern for 3.2mm x 2.5mm crystal)



本目录中的产品规格以截至2020年1月的为准。若有变更恕不另行通知。

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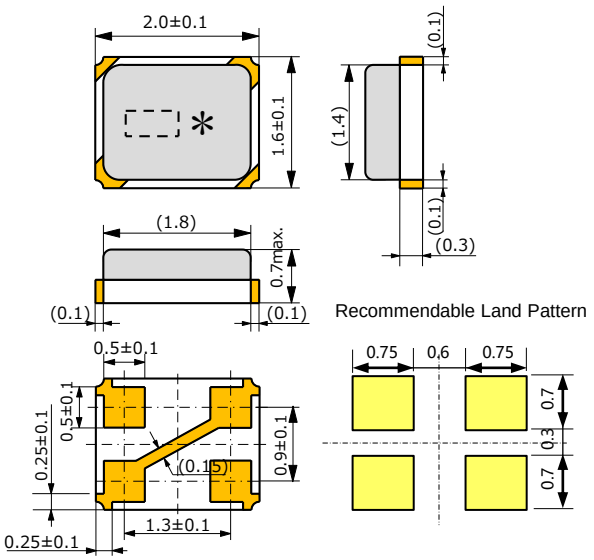
产品一览

系列	型号	频率(MHz)	频率公差 (ppm max.)	频率温度特性 (ppm max.)	ESR (ohm max.)	频率老化 (ppm/Y)	负载电容量 (pF)
XRCGB_F_S	XRCGB24M000FFS1AR0	24.0000	±8	±12 (-30 ～ +85 ℃)	70	±2	6.0
	XRCGB26M000F1S1AR0	26.0000	±10	±10 (-30 ～ +85 ℃)	60		
	XRCGB32M000F1S1AR0	32.0000			50		
	XRCGB37M400F1S1AR0	37.4000			60		
	XRCGB38M400F1S1AR0	38.4000					
	XRCGB40M000F1S1AR0	40.0000			50		
	XRCGB24M000F1SBAR0	24.0000		±20 (-40 ～ +105 ℃)	70		
	XRCGB26M000F1SBAR0	26.0000			60		
	XRCGB32M000F1SBAR0	32.0000			50		
	XRCGB37M400F1S2FR0	37.4000			60		
	XRCGB38M400F1S2FR0	38.4000					
	XRCGB40M000F1S2FR0	40.0000			50		
XRCGB_F_N	XRCGB16M000FXN00R0	16.0000	±40(Total) (-30 ～ +85 ℃)		200	±5	
XRCGB_F_P	XRCGB24M000F2P00R0	24.0000	±20	±20 (-30 ～ +85 ℃)	150		
	XRCGB25M000F2P00R0	25.0000	±20	±20 (-30 ～ +85 ℃)			
	XRCGB26M000F2P00R0	26.0000					
	XRCGB27M000F2P00R0	27.0000					
	XRCGB27M120F2P00R0	27.1200					
	XRCGB30M000F2P00R0	30.0000			100		
	XRCGB31M250F2P00R0	31.2500					
	XRCGB32M000F2P00R0	32.0000					
XRCGB_F_M	XRCGB24M576F3M00R0	24.5760	±30	±40 (-30 ～ +85 ℃)	150		
	XRCGB33M868F4M00R0	33.8688	±45	±40 (-30 ～ +85 ℃)	100		
	XRCGB40M000F4M00R0	40.0000					

*关于产品如有任何要求，请联系村田销售或技术人员。

尺寸规格和推荐焊盘

(in mm)



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